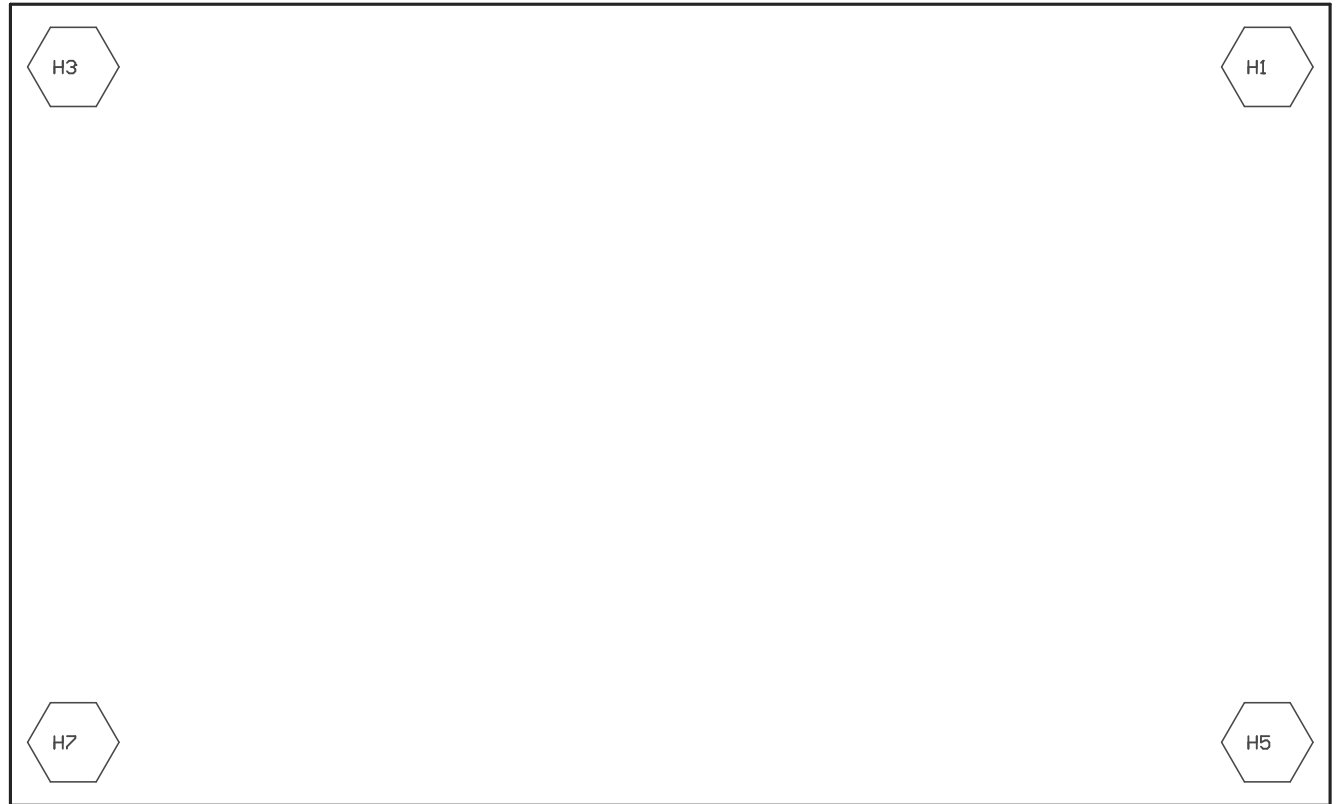


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20852	REV: A	SUN REV: Not In VersionControl
	TID #: PMP20852		
PLOT NAME = Top Assembly Drawing	GENERATED : 11/17/2017	8:35:53 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20852	REV: A	SVN REV: Not In VersionControl
	TID #: PMP20852		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/17/2017 8:35:54 AM		TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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